

P-Channel 30 V (D-S) MOSFET

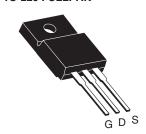
PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a		
- 30	0.011 at V _{GS} = - 10 V	55		
- 30	0.013 at V _{GS} = - 4.5 V	50		

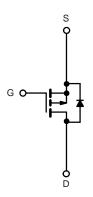
FEATURES

• Compliant to RoHS Directive 2002/95/EC









P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Gate-Source Voltage	V _{GS}	± 20	V			
Ocationary Project Ocamout (T., 475.00)	T _C = 25 °C		- 55 ^a			
Continuous Drain Current ($T_J = 175 ^{\circ}\text{C}$)	T _C = 125 °C	l _D	- 45	А		
Pulsed Drain Current	I _{DM}	- 260	7			
Avalanche Current	I _{AR}	- 55				
Repetitive Avalanche Energy ^b	L = 0.1 mH	E _{AR}	190	mJ		
Davies Dissipation	T _C = 25 °C (TO-220F)	В	45 ^d	W		
Power Dissipation	T _A = 25 °C (TO-220F) ^c	$ P_D$	3.75			
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Limit	Unit		
Junction-to-Ambient	PCB Mount (TO-263) ^c	В	40			
Junction-to-Ambient	Free Air (TO-220AB)	R _{thJA}	A 62.5	°C/W		
Junction-to-Case		R _{thJC}	0.8	1		

Notes:

- a. Package limited.
- b. Duty cycle \leq 1 %.
- c. When mounted on 1" square PCB (FR-4 material).
- d. See SOA curve for voltage derating.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS} $V_{GS} = 0 \text{ V, } I_{D} = -250 \mu\text{A}$		- 30			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 1		- 3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = - 30 V, V _{GS} = 0 V			- 1	- 50 μA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 125 °C			- 50		
		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 175 °C			- 250		
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 120			Α	
		V _{GS} = - 10 V, I _D = - 30 A		0.011			
Drain-Source On-State Resistance ^a	Ь	V _{GS} = - 10 V, I _D = - 30 A, T _J = 125 °C		0.015			
Diam-Source On-State Resistance	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 30 A, T _J = 175 °C		0.019		Ω	
		V _{GS} = - 4.5 V, I _D = - 20 A		0.013		=	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 75 A	20			S	
Dynamic ^b							
Input Capacitance	C _{iss}			4500		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = -25 \text{ V}, f = 1 \text{ MHz}$		765			
Reversen Transfer Capacitance	C _{rss}			315			
Total Gate Charge ^c	Qg			80	120	nC	
Gate-Source Charge ^c	Q _{gs}	V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 75 A		20			
Gate-Drain Charge ^c	Q _{gd}]		15			
Turn-On Delay Time ^c	t _{d(on)}			25	40	ns	
Rise Time ^c	t _r	$V_{DD} = -15 \text{ V}, R_1 = 0.2 \Omega$		225	360		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong -75 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 2.5 \Omega$		150	240		
Fall Time ^c	t _f			210	340		
Source-Drain Diode Ratings and Cha	racteristics ^b	(T _C = 25 °C)					
Continuous Current	I _S				- 80	A	
Pulsed Current	I _{SM}				- 240		
Forward Voltage ^a	V _{SD}	I _F = -75 A, V _{GS} = 0 V		- 1.2	- 1.5	V	
Reverse Recovery Time	t _{rr}			55	100	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 75 A, dl/dt = 100 A/μs		2.5	5	Α	
Reverse Recovery Charge	Q _{rr}	1		0.07	0.25	μC	

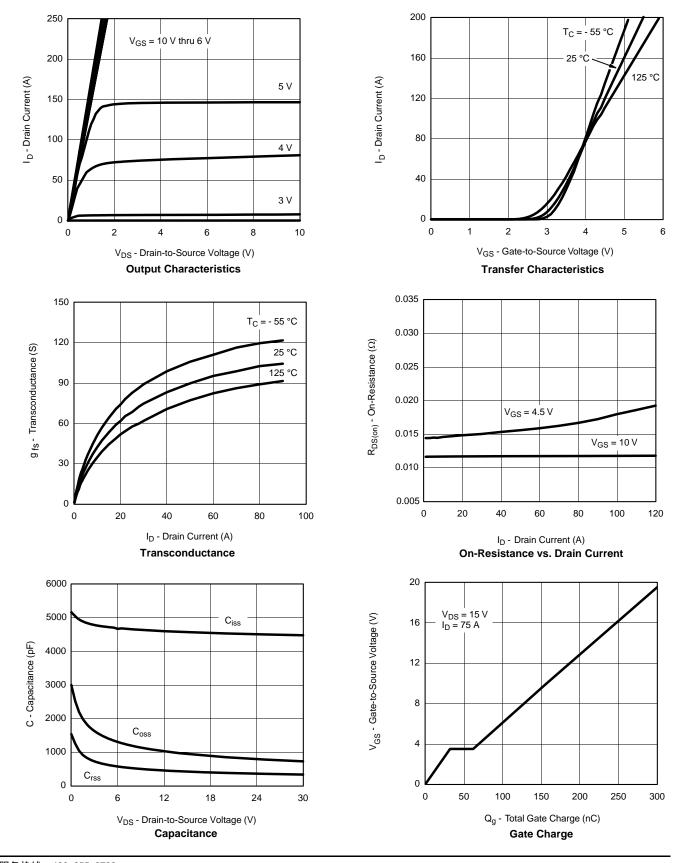
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

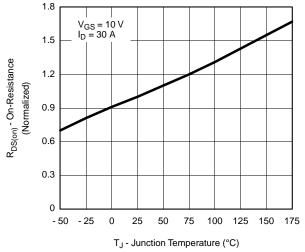


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

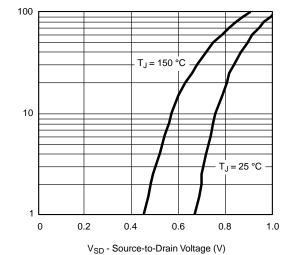




TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

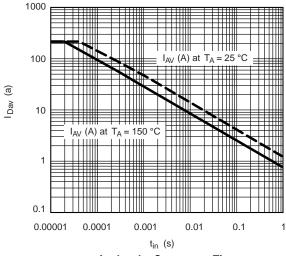


On-Resistance vs. Junction Temperature

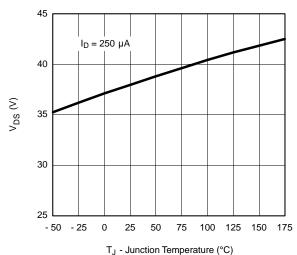


I_S - Source Current (A)

Source-Drain Diode Forward Voltage



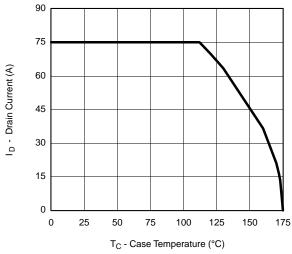
Avalanche Current vs. Time

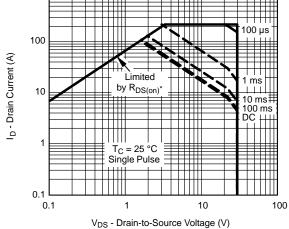


Drain Source Breakdown vs. Junction Temperature



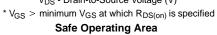
THERMAL RATINGS

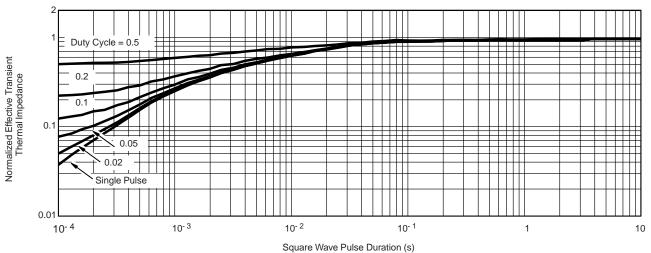




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Maximum Avalanche and Drain Current vs. Case Temperature

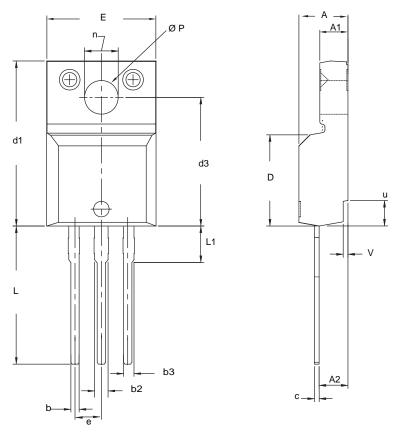




Normalized Thermal Transient Impedance, Junction-to-Case



TO-220 FULLPAK



	MILLI	METERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.570	4.830	0.180	0.190	
A1	2.570	2.830	0.101	0.111	
A2	2.510	2.850	0.099	0.112	
b	0.622	0.890	0.024	0.035	
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
С	0.440	0.629	0.017	0.025	
D	8.650	9.800	0.341	0.386	
d1	15.88	16.120	0.622	0.635	
d3	12.300	12.920	0.484	0.509	
E	10.360	10.630	0.408	0.419	
е	2.54 BSC		0.100 BSC		
L	13.200	13.730	0.520	0.541	
L1	3.100	3.500	0.122	0.138	
n	6.050	6.150	0.238	0.242	
ØΡ	3.050	3.450	0.120	0.136	
u	2.400	2.500	0.094	0.098	
V	0.400	0.500	0.016	0.020	
ECN: X09-0126-Rev. B, DWG: 5972	26-Oct-09				

- To be used only for process drawing.
 These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads.
 All critical dimensions should C meet C_{pk} > 1.33.
 All dimensions include burrs and plating thickness.
 No chipping or package damage.



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